



Material Content Data Sheet



Sales Product Name		ICE2PCS02		Issued		31. October 2014		
MA#		MA001051856						
Package		PG-DIP-8-12		Weight*		545.58 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.787	0.33	0.33	3275	3275
leadframe	inorganic material	phosphorus	7723-14-0	0.050	0.01		91	
	non noble metal	zinc	7440-66-6	0.198	0.04		363	
	non noble metal	iron	7439-89-6	3.961	0.73		7261	
wire	non noble metal	copper	7440-50-8	160.843	29.48	30.26	294809	302524
	noble metal	gold	7440-57-5	0.217	0.04	0.04	398	398
	encapsulation	organic material	carbon black	1333-86-4	1.108	0.20		2032
encapsulation	plastics	epoxy resin	-	35.838	6.57		65688	
	inorganic material	silicondioxide	60676-86-0	332.519	60.95	67.72	609472	677192
leadfinish	non noble metal	tin	7440-31-5	7.496	1.37	1.37	13739	13739
plating	noble metal	silver	7440-22-4	0.407	0.07	0.07	747	747
glue	plastics	acrylic resin	-	0.232	0.04		425	
	noble metal	silver	7440-22-4	0.927	0.17	0.21	1700	2125
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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